

Product Change Notification - KSRA-21IGTK891

Date: 23 Nov 2017
Product Category: Ethernet Controllers
Notification subject: CCB 3196 Initial Notice: Qualification of CEL-9750ZHF10AKL molding compound for KSZ8695 products available in 289L BGA package assembled at ASE assembly site.
Notification text: **PCN Status:**
Initial notification

PCN Type:
Manufacturing Change

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of CEL-9750ZHF10AKL molding compound for KSZ8695 products available in 289L BGA package assembled at ASE assembly site.

Pre Change:

Using EME-G770J Molding compound material

Post Change:

Using CEL-9750ZHF10AKL Molding compound material

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	ASE Inc. (ASE)	ASE Inc. (ASE)
Wire material	Gold (Au) Wire	Gold (Au) Wire
Die attach material	2100A	2100A
Molding compound material	EME-G770J	CEL-9750ZHF10AKL
Solder Ball Alloy	SAC105	SAC105

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve manufacturability by qualifying CEL-9750ZHF10AKL molding compound.

Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

April 2018

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

Workweek	November 2017					-->	April 2018				
	44	45	46	47	48		14	15	16	17	18
Initial PCN Issue Date				X							
Qual Report Availability								X			
Final PCN Issue Date								X			

Method to Identify Change:

Traceability code

Qualification Plan:

Please open the attachments included with this PCN labeled as PCN_#_Qual Plan.

Revision History:

November 23, 2017: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

- [PCN_KSRA-21IGTK891_Affected CPN.pdf](#)
- [PCN_KSRA-21IGTK891_Qual Plan.pdf](#)
- [PCN_KSRA-21IGTK891_Affected CPN.xlsx](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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KSRA-21IGTK891-CCB 3025 CCB 3196 Initial Notice: Qualification of CEL-9750ZHF10AKL molding compound for KSZ8695 products available in 289L BGA package assembled at ASE assembly site.

Affected Catalog Part Numbers (CPN)

PCN_KSRA-21IGTK891
CATALOG_PART_NBR
KSZ8695P
KSZ8695PI
KSZ8695PX